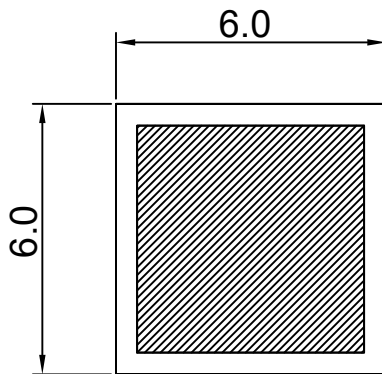


RoHS

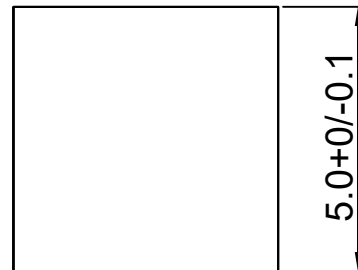
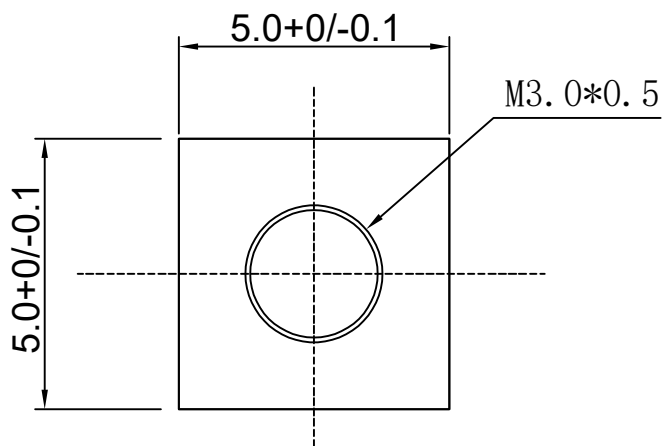
REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25



PCB LAYOUT

技术要求:

- 1.打铜底 $0.5-1\mu\text{m}$,镍 $2-2.5\mu\text{m}$, 镀雾锡 $3-5\mu\text{m}$ 。
- 2.铆好后不得有松动现象。
- 3.插脚尖部符合可焊性要求。
- 4.螺纹需符合通止规/止针要求。
- 5.螺纹扭矩: 0.6Nm 。
- 6.额定电流: 30A 。



>30.±0.4	X.°±
6-30±0.3	.X°±
0-6±0.2	.XX°±
ANGLES±1°	.XXX°±
UNITS:	mm

PART NO: TS30000		XFCN 兴飞连接器		
TITLE: PCB SOLDERING TERMINAL		0769-82001899		
		www.xfconn.com		
		DWG NO: /		
APPD	Chen ZhiQiang	VIEW		
CHKD	Liu Wei	SCALE	SHEET	REV
DRAW	Chen HongJiang	NONE	1/1	A1
DATE	2024.09.02			

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序号	名称	零件编号	材质	数量
1	插脚		H62 (Y2)	1